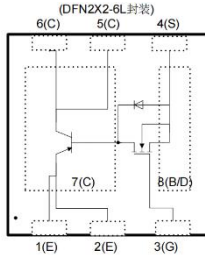


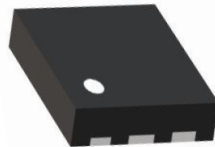
1. General Description

The SSC8P22CN2-CN combination of -30V -3A PNP low VCEsat Breakthrough In Small Signal (BISS) transistor and 20V N-channel Trench MOSFET.

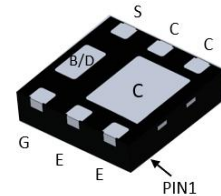
The device is housed in a small and ultra thin DFN2*2 Surface-Mounted Device (SMD) plastic package.



Schematic Diagram



DFN2020-6L



Pin configuration

2. Specification Features

- High Power and current handling capability
- High collector current capability -3A I_C
- High energy efficiency due to less heat generation
- High Power and current handling capability
- Smaller required Printed-Circuit Board (PCB)

3. Application

- Charging circuits
- Load switch
- Power management
- Battery-driven devices
- PWM applications
- Power switches (e.g. motors, fans)

4. Absolute Maximum Ratings ($T_J = 25^\circ\text{C}$)

Parameter (PNP)	Symbol	Value	Units
Collector-emitter Voltage	V_{CEO}	-30	V
Collector-base Voltage	V_{CBO}	-30	V
Emitter-base Voltage	V_{EBO}	-6	V
Continues Collector Current ^b	I_C	-3	A
Pulse Collector Current ^c	I_{CM}	-3.5	A
Power dissipation ^a	P_D	1.5	W

5. Thermal resistance ratings

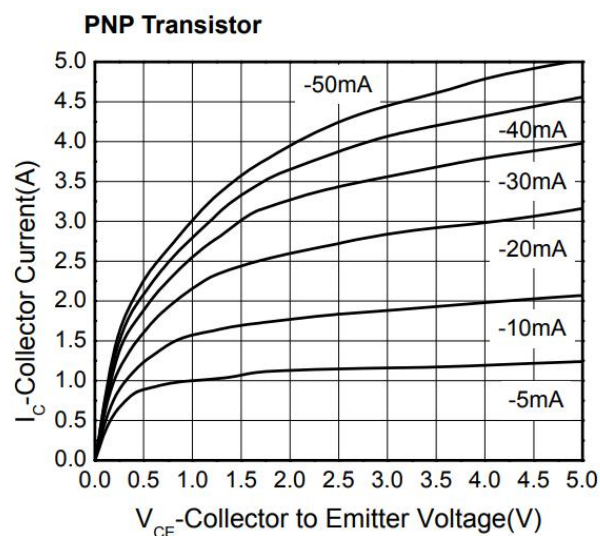
Parameter	Symbol	Value	Units
Junction-to-Ambient Thermal Resistance ^a	R _{θJA}		°C/W
Junction-to-Ambient Thermal Resistance ^b	R _{θJA}	90	°C/W

- Surface mounted on FR-4 Board using 1 square inch pad size, 1oz copper
- Surface mounted on FR-4 board using minimum pad size, 1oz copper
- Pulse width=300μs, Duty Cycle<2%
- Maximum junction temperature T_J=150°C.

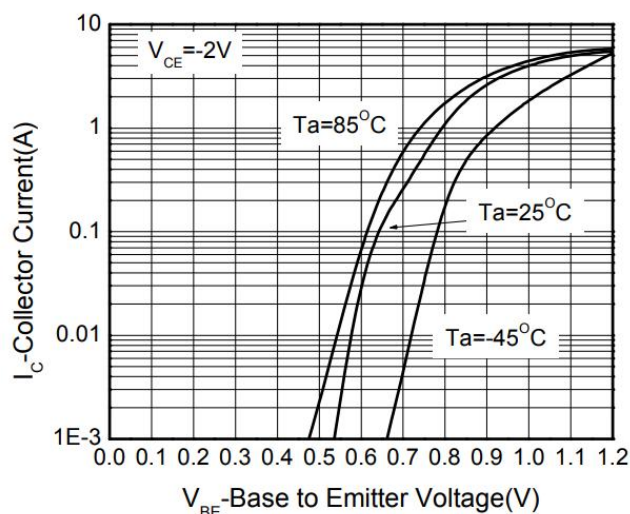
6. Electrical Characteristics (T_J =25°C)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
PNP Transistor						
Collector-emitter Breakdown Voltage	BV _{CEO}	I _C =10mA, I _B =0mA	-30			V
Collector-base Breakdown Voltage	BV _{CBO}	I _C =1mA, I _E =0mA	-30			V
Emitter-base Breakdown Voltage	BV _{EBO}	I _E =-100μA, I _C =0mA	-6			V
Collector Cutoff Current	I _{CBO}	V _{CB} =-30V, I _E =0			-100	nA
Emitter Cutoff Current	I _{EBO}	V _{EB} =-5V, I _C =0			-100	nA
Collector-emitter Saturation Voltage	V _{CE(sat)}	I _C =-0.5A, I _B =-50mA		-0.1	-0.35	V
Base-emitter Saturation Voltage	V _{BE(sat)}	I _C =-0.5A, I _B =-50mA		-0.9	-1.5	V
Base-emitter Forward Voltage	V _{BE(on)}	I _C =-0.5A, V _{CE} =-2V		-0.7	-1.1	V
Dc Current Gain	h _{FE}	I _C =-0.5A, V _{CE} =-2V	100		300	
NMOS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250uA	20			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =16V, V _{GS} =0V			0.1	uA
Gate-body leakage current	I _{GSS}	V _{GS} =±4.5V, V _{DS} =0V			±1	uA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	0.45	0.75	1.5	V
Drain-source on-resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =0.5A			1.5	Ω
		V _{GS} =2.5V, I _D =0.5A			4	
Diode forward voltage	V _{SD}	I _S =0.5A, V _{GS} =0V		0.7	1.3	V

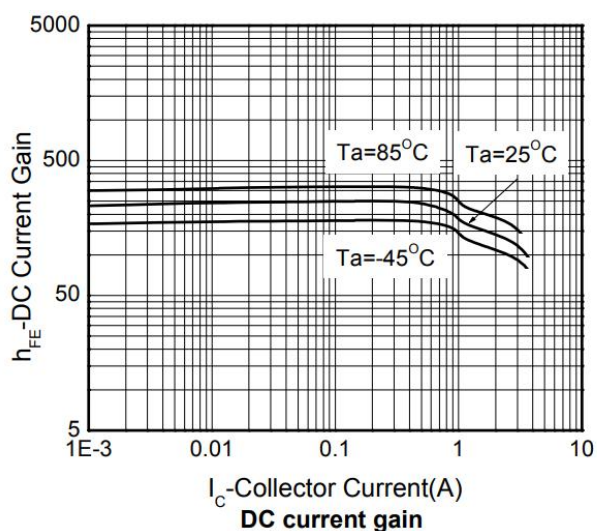
7. Typical Electrical and Thermal Characteristics (Curves)



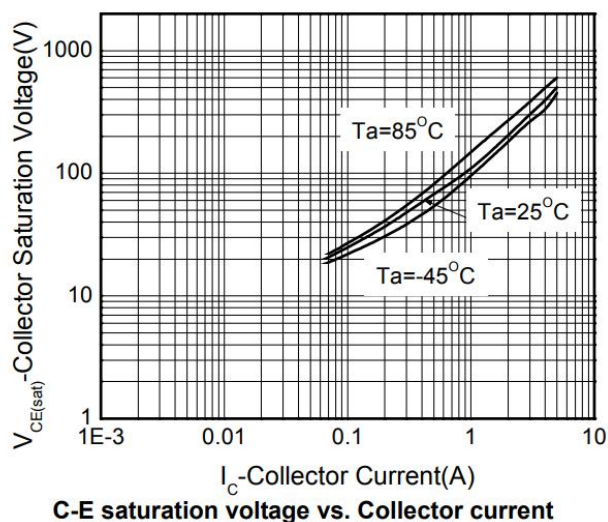
Output characteristics



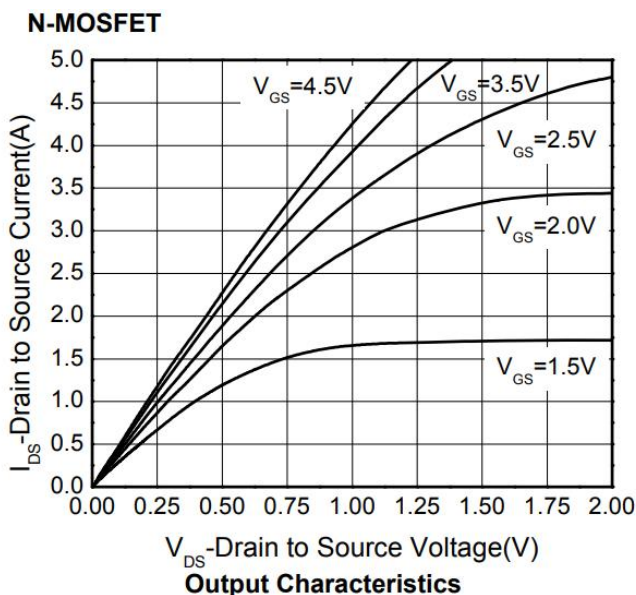
Transfer characteristics



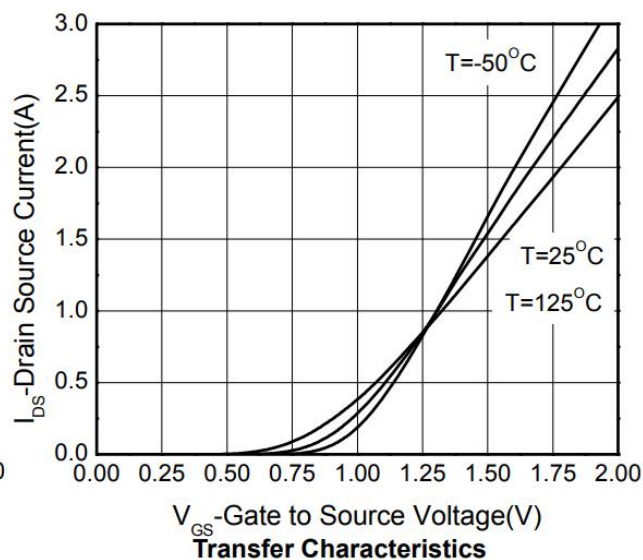
DC current gain



C-E saturation voltage vs. Collector current



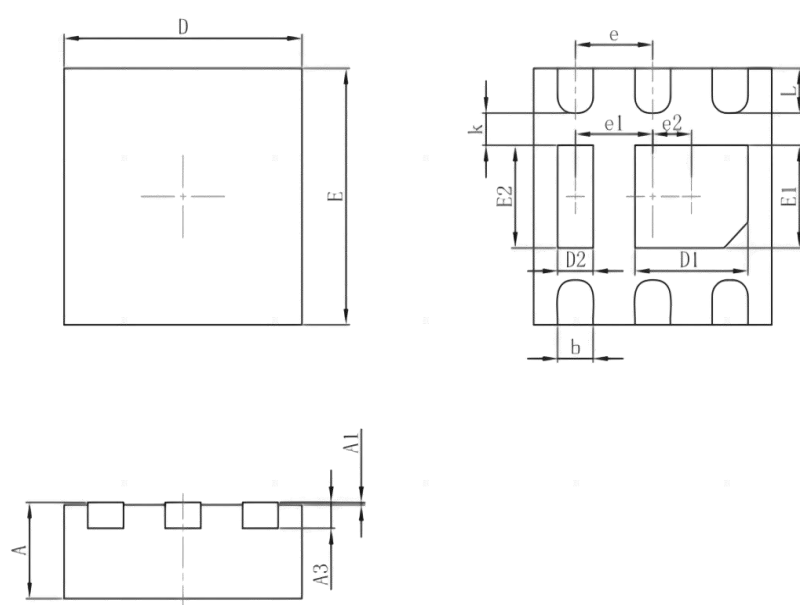
Output Characteristics



Transfer Characteristics

8. Package Outline Dimensions

Device Marking	Device	Package	Reel size	Tape width	Quantity
M2019 A***	SSC8P22CN2-CN	DFN2020-6L	7inch	8mm	4000



Symbol	Dimensions Millimeters		
	Mlin.	Typ.	Max.
A	0.70		0.80
A1	-		0.05
A3	0.203REF		
D	1.924	2.000	2.076
E	1.924	2.000	2.076
D1	0.850	0.950	1.050
E1	0.700	0.800	0.900
D2	0.200	0.300	0.400
E2	0.700	0.800	0.900
e1	0.650Typ.		
e2	0.325Typ.		
k	0.200Min.		
b	0.250	0.300	0.350
e	0.650Typ.		
L	0.300	0.350	0.400

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